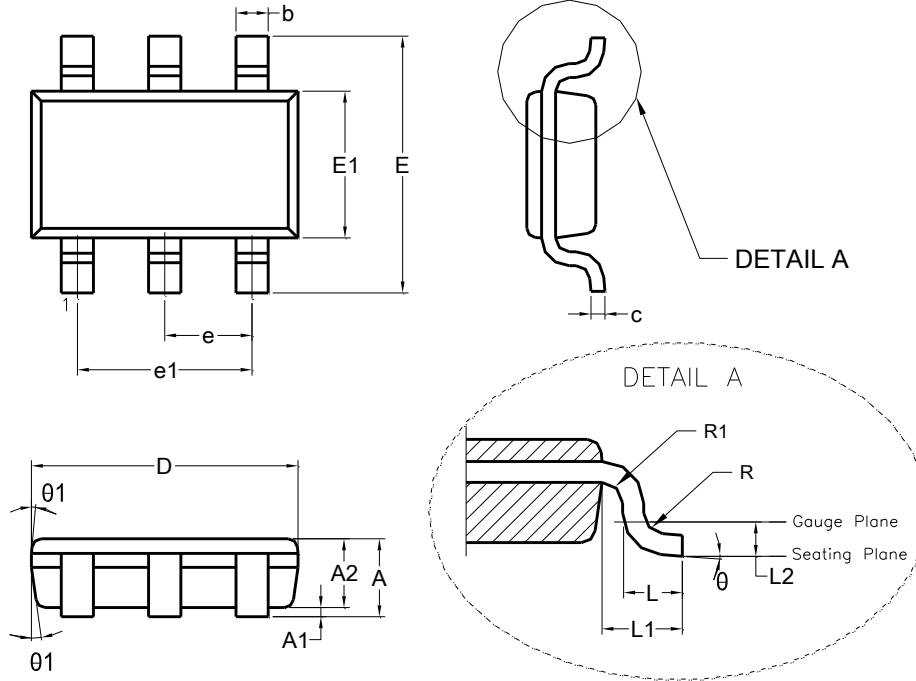


Package Outline Dimensions

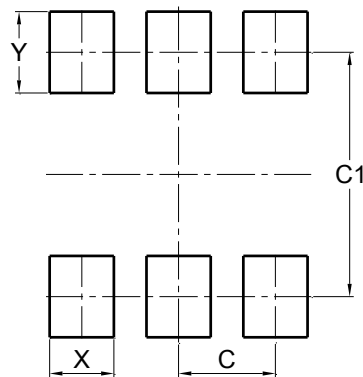
TSOT26 (Type A1)



TSOT26 (Type A1)			
Dim	Min	Max	Typ
A	0.700	0.825	--
A1	0.000	0.050	--
A2	0.700	0.775	0.750
b	0.350	0.500	--
c	0.100	0.200	--
D	2.800	3.000	2.900
E	2.600	3.000	2.800
E1	1.500	1.700	1.600
e	0.95 BSC		
e1	1.900 BSC		
L	0.370	0.600	0.450
L1	0.600 REF		
L2	0.250 BSC		
R	0.100	--	--
R1	0.100	0.250	--
theta	0°	8°	4°
theta1	4°	12°	10°
All Dimensions in mm			

Suggested Pad Layout

TSOT26 (Type A1)



Dimensions	Value (in mm)
C	0.950
C1	2.400
X	0.630
Y	0.800

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.